

Electronic Patent Application Fee Transmittal

Application Number:	10776203			
Filing Date:	12-Feb-2004			
Title of Invention:	Method & apparatus for multi-stage sputter deposition of uniform thickness layers			
First Named Inventor/Applicant Name:	Rajiv Yadav Ranjan			
Filer:	Aamer S. Ahmed/Alexis Boyd			
Attorney Docket Number:	50103-553			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	540	540
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 2 months with \$0 paid	1252	1	490	490
Miscellaneous:				
Total in USD (\$)				1030